Also published as:

SPUTTERING TARGET MATERIAL

Publication number: WO02077317 (A1)

Publication date: Inventor(s):	2002-10-03 HASEGAWA KOICHI [JP]; ISHII NOBUO [JP]; ASAKI TOMOYOSHI [JP] *		EP1371749 (A1) EP1371749 (B1) JS2004055882 (A1) US7465424 (B2)
Applicant(s):	ISHIFUKU METAL IND [JP]; HASEGAWA KOICHI [JP]; ISHII NOBUO [JP]; ASAKI TOMOYOSHI [JP] +		TW575674 (B)
Classification:		C	Cited documents:
- international:	C22C5/06; C22C5/08; C23C14/14; C23C14/34; G11B7/258; G11B7/26; C22C5/06; C23C14/14; C23C14/34; G11B7/24; G11B7/26; (IPC1-7): C22C5/06; C23C14/14; C23C14/34; G09F9/30; G11B7/26; H05B33/10; H05B33/14; H05B33/24		JP2001357559 (A) JP11025515 (A) JP10177742 (A) JP2000109943 (A) JP9111380 (A)
- European:	C22C5/06; C22C5/08; C23C14/14; C23C14/34B2; G11B7/258D; G11B7/26		
Application number: WO2002JP02466 20020315			

Abstract of WO 02077317 (A1)

Priority number(s): JP20010076132 20010316

A sputtering target material which comprises an Ag alloy comprising Ag, a specific small amount of a metal component (A) selected from among In, Sn and Zn and a specific small amount of a metal component (B) selected from among Au, Pd and Pt and optionally a small amount of Cu. The sputtering target material has a high reflectance and also exhibits excellent resistance to sulfurization.

Data supplied from the *espacenet* database — Worldwide